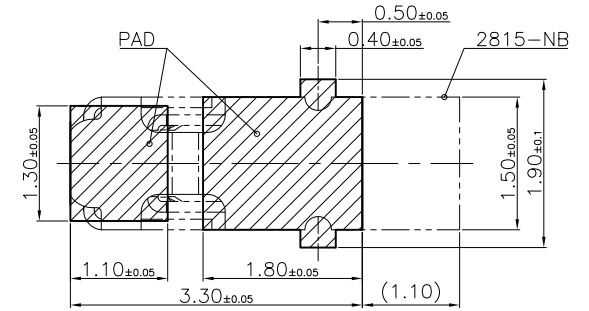
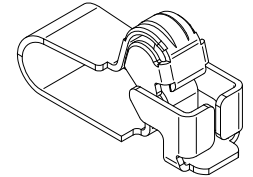
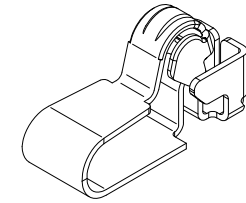
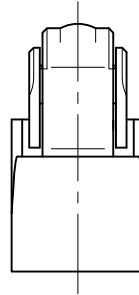
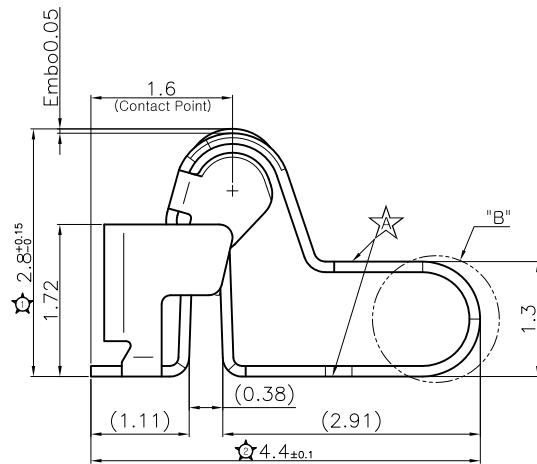


SIMULATION

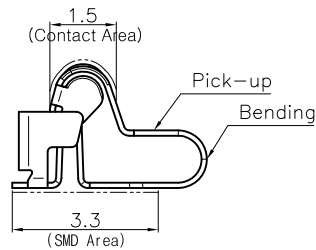
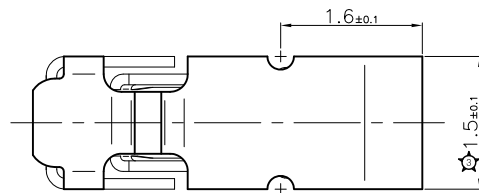


RECOMMENDED PCB LAYOUT(Top View)



*NOTE

- PLATING
 - Contact Area : Au 0.1 μ m Min over Ni 1.5~4.0 μ m.
 - SMD Area : Au 0.05 μ m Min over Ni 1.50~4.0 μ m.
 - Bending & Pick-up : Ni 1.5~3.5 μ m.
- ☆: C.T.Q
- ☆: 평탄도 0.05 Max.
- Contact 가동거리(Max)는 0.6mm 이상으로 한다.
- Contact 가동거리 : 1.0mm
권장 Contact 높이 : 가동거리의 60~80% 범위 내 (0.60~0.80mm) => (2.0~2.2mm)
- 제품의 안정적 Contact을 위하여 Bending部 "B" 주위에 기구적인 간섭이 없을 것.
- 일반 공차 ±0.1 적용 할 것.



PLATING AREA

1	Contact	Ti-Cu	Note.1	t0.12
No	Descriptions	Material	Finish	Remarks
General Tolerance		Scale N/S	Units mm	Sheet
Dimension mm (°)		Date 2013. 08. 16	1 of 1	
x	± 0.2	Drawn	Design	Checked
x.x	± 0.1	J.S. Kim	Y.J. Park	S.K. Hong
x.xx	± 0.05	2013/08/20	2013/08/20	2013/08/20
x.xxx	± 0.01	HYUJIN CONNECTOR		
ANGLE	± 1°			
TITLE		HJ-2815-NB		Rev.
		ANTENNA CONTACT		
Customer Drawing				
SW No.				
DWG No.		HJ-2815-NB-A1		0